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L Number	Hits	Search Text	DB	Time stamp
1	3111	257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls.	USPAT;	2003/07/23 09:48
_		438/627.ccls. 438/643.ccls. 438/653.ccls.	US-PGPUB	
2	1095	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls.	USPAT;	2003/07/23 09:50
		438/627.ccls. 438/643.ccls. 438/653.ccls.) and (copper cu	US-PGPUB	
		platinum pt) and (platinum pt osmium os ruthenium ru		
		iridium ir rhodium rh)		
3	751	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls.	USPAT;	2003/07/23 09:54
		438/627.ccls. 438/643.ccls. 438/653.ccls.) and ((copper cu	US-PGPUB	
		platinum pt) with (platinum pt osmium os ruthenium ru		
_		iridium ir rhodium rh))	LICDATE	2002/07/22 00 52
4	409	((257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls.	USPAT;	2003/07/23 09:52
		438/627.ccls. 438/643.ccls. 438/653.ccls.) and (copper cu	US-PGPUB	
		platinum pt) and (platinum pt osmium os ruthenium ru iridium ir rhodium rh)) and (electromigrat\$5 void)		
5	402	(((257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls.	USPAT;	2003/07/23 09:52
3	702	438/627.ccls. 438/643.ccls. 438/653.ccls.) and (copper cu	US-PGPUB	2003/07/23 03.32
		platinum pt) and (platinum pt osmium os ruthenium ru	05 1 01 05	
		iridium ir rhodium rh)) and (electromigrat\$5 void)) and		
		(interconnect\$6 diffusion barrier)		
7	1466	((((CU OR COPPER) WITH INTERCON\$10)) AND	USPAT;	2003/07/23 09:56
		(DIFFUSION ADJ BARRIER))	US-PGPUB	
8	392	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls.	USPAT;	2003/07/23 09:56
		438/627.ccls. 438/643.ccls. 438/653.ccls.) and (((((CU OR	US-PGPUB	
		COPPER) WITH INTERCON\$10)) AND (DIFFUSION ADJ		
_		BARRIER)))		2002/07/22 00 57
9	49	(((pt OR platinum) WITH INTERCON\$10)) same (diffusion	USPAT;	2003/07/23 09:57
40	224	adj barrier)	US-PGPUB	2003/07/23 09:57
10	234	((RU OR RUTHENIUM or pt or ir or os or rh or iridium or platinum or osmium or rhodium) same electromigration)	USPAT; US-PGPUB	2003/07/23 09:57
11	179	(((RU OR RUTHENIUM or pt or ir or os or rh or iridium or	EPO; JPO;	2003/07/23 09:57
11	1/9	platinum or osmium or rhodium) and electromigration)) and	DERWENT;	2003/01/23 03.31
		(copper or cu)	IBM_TDB	
12	216	((RU OR RUTHENIUM) and (DIFFUSION ADJ BARRIER))	EPO; JPO;	2003/07/23 09:58
			DERWENT;	
			IBM_TDB	
13	30	((RUTHENIUM or iridium or platinum or osmium or rhodium)	EPO; JPO;	2003/07/23 09:58
		and electromigration)	DERWENT;	
			IBM_TDB	
6	46	(257/762.ccls. 257/767.ccls. 257/768.ccls. 257/751.ccls.	USPAT;	2003/07/23 09:58
		438/627.ccls. 438/643.ccls. 438/653.ccls.) and ((copper cu	US-PGPUB	
		platinum pt) same (interconnect\$6 diffusion barrier) same		
		(platinum pt osmium os ruthenium ru iridium ir rhodium rh)		
		same (electromigrat\$5 void))		<u> </u>